

Wire-wound Type Power Inductor

SCWL252010XXXXQ Series

Features

- u This specification applies Low Profile Power Inductors
- u Halogen free, Lead Free, RoHS Compliance

Applications

SCWL252010XXXXQ series is generic applied in portable DC to DC converter line.

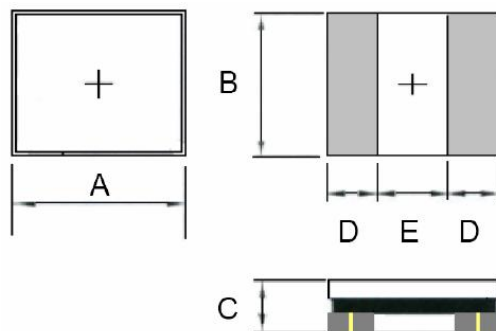
- u Mobile phones
- u HDDs
- u DSCs
- u PADs
- u LCD, LED display, etc.

Part Numbering

SCWL	2520	10	2R2	M	T	F	Q
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

- 1 Product Series
- 2 Size Code: the first two digitals : length(mm), the last two digitals : width(mm)
- 3 Thickness (mm)
- 4 Inductance (μH), eg. 2R2=2.2 μH ; R47=0.47 μH
- 5 Inductance tolerance, M: $\pm 20\%$; Y: $\pm 30\%$
- 6 Packaging: T - Embossed plastic tape, 7" reel.
- 7 Soldering : Green Parts, F - Lead-Free for whole chip
- 8 Model Code

Construction & Dimensions



Symbol	252010
A	2.5 -0.1/+0.2
B	2.0 -0.5/+0.35
C	1.02 Max
D	0.85 REF
E	0.80 REF

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Electrical Characteristics

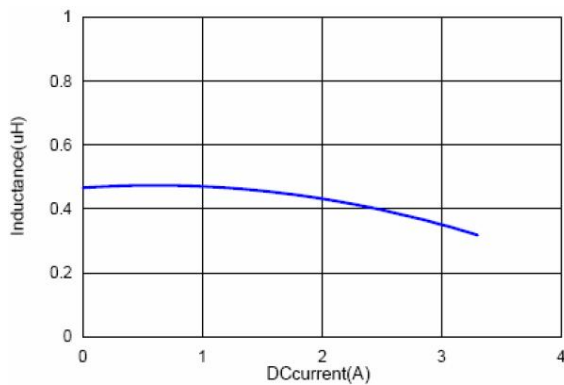
Part Number	Inductance (μ H)	Tolerance (%)	Test Frequency (Hz)	DCR (Ω) $\pm 20\%$	I sat (A)		I rms (A)	
					Typ.	Max.	Typ.	Max.
SCWL252010R47YTFQ	0.47	$\pm 30\%$	0.1V / 1M	0.030	2.85	2.57	2.80	2.50
SCWL252010R68YTFQ	0.68	$\pm 30\%$	0.1V / 1M	0.039	2.70	2.45	2.45	2.20
SCWL2520101R0YTFQ	1.0	$\pm 30\%$	0.1V / 1M	0.055	2.45	2.05	2.20	1.80
SCWL2520101R5YTFQ	1.5	$\pm 30\%$	0.1V / 1M	0.090	1.80	1.70	1.70	1.55
SCWL2520102R2MTFQ	2.2	$\pm 20\%$	0.1V / 1M	0.125	1.60	1.55	1.55	1.40
SCWL2520104R7MTFQ	4.7	$\pm 20\%$	0.1V / 1M	0.250	1.10	0.95	1.05	0.92

Note:

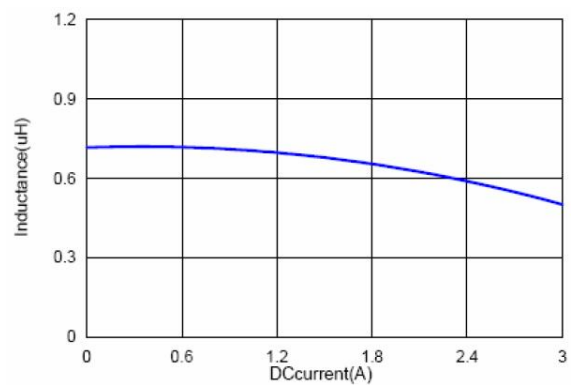
1. Isat: Based on inductance change ($\Delta L/L_0: \leq -30\%$) @ ambient temp. 25°C
2. Irms: Based on temperature rise ($\Delta T: 40^\circ\text{C typ.}$)

Current Characteristics

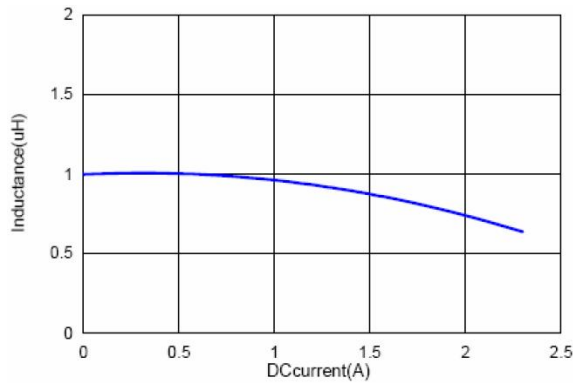
SCWL252010Q-R47Y-ZF



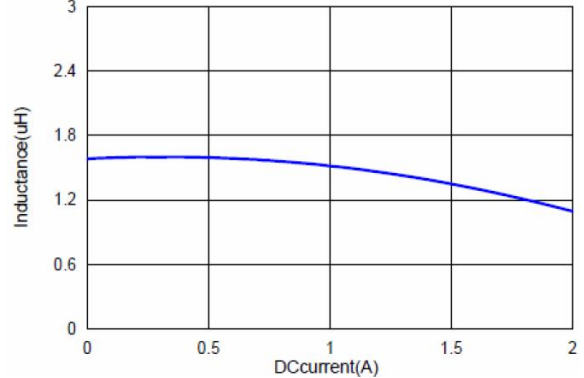
SCWL252010Q-R68Y-ZF



SCWL252010Q-1R0Y-ZF



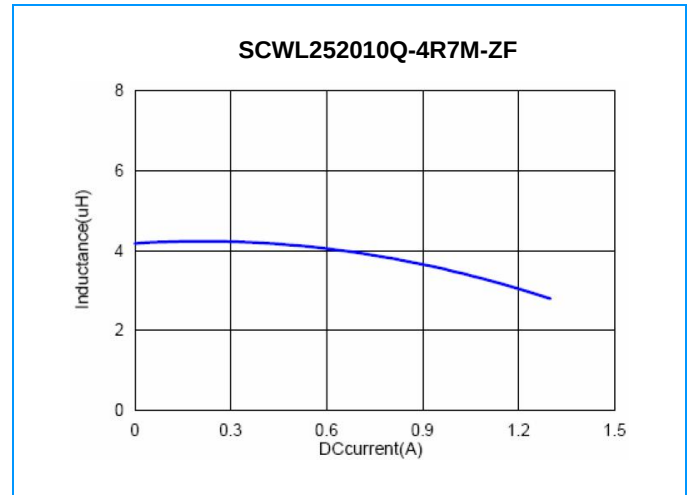
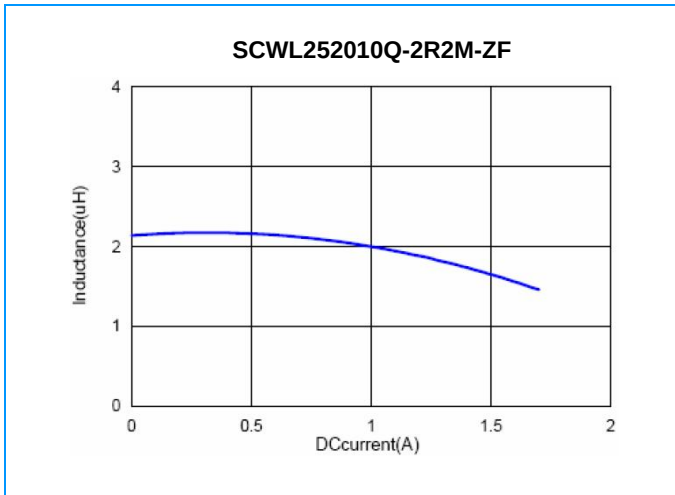
SCWL252010Q-1R5Y-ZF



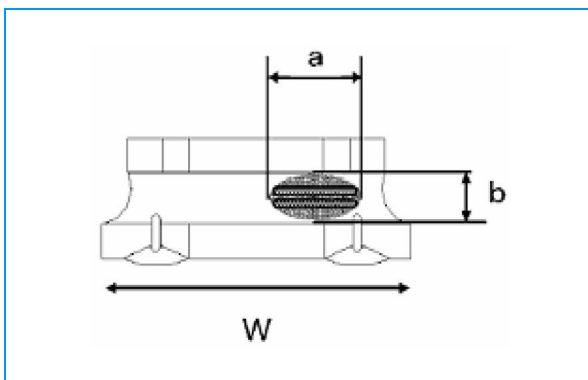
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Current Characteristics



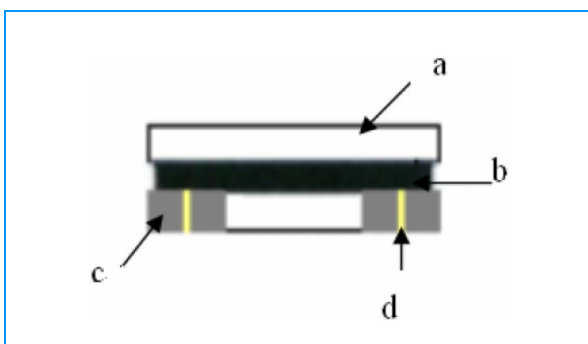
Appearance



Exposed wire tolerance limit of coating resin part on product side. Size of exposed wire occurring to coating resin is specified below.

1. Width direction (dimension a): Acceptable when $a \leq w/2$
Nonconforming when $a > w/2$
2. Length direction (dimension b): Dimension b is not specified.
3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.

Material Lists



No.	Item	Material
a	Core	Ferrite Core
b	Coating	Epoxy with magnetic powder
c	Termination	Tin (Pb-Free)
d	Wire	Enameled Copper Wire

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Soldering and Mounting

Soldering

Mildly activated rosin fluxes are preferred. SOCAY terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

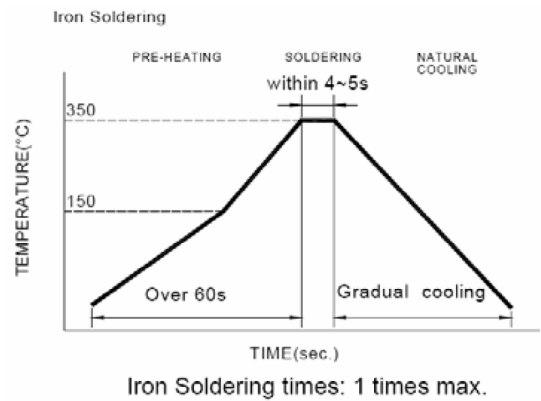
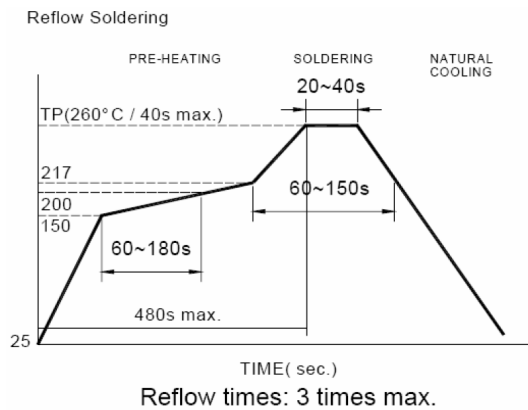
Solder re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

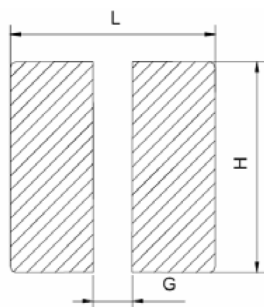
Solder Iron (Figure 2):

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- u Preheat circuit and products to 150 °C
- u Never contact the ceramic with the iron tip
- u Use a 20 watt soldering iron with tip diameter of 1.0mm
- u 355 °C tip temperature (max)
- u 1.0mm tip diameter (max)
- u Limit soldering time to 4~5 sec.



Recommended PCB Board Pattern



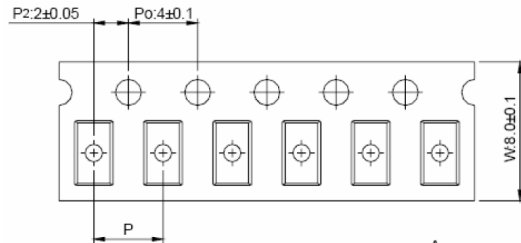
L (mm)	G (mm)	H (mm)
2.9	0.8	2.4

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Packaging Information

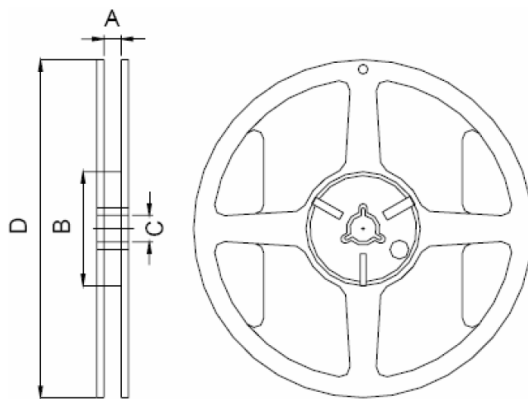
Tape Dimension



Bottom View

Symbol	252010
A0 (mm)	2.85 ± 0.1
B0 (mm)	2.45 ± 0.1
K0 (mm)	1.40 ± 0.1
P (mm)	4.00 ± 0.1
t (mm)	0.23 ± 0.05

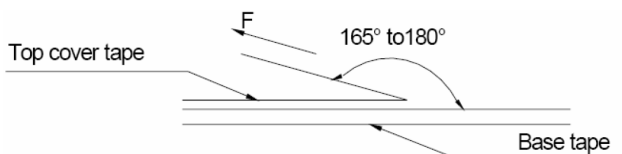
Reel Dimension



7"x8mm

Symbol	7" × 8 mm
A (mm)	8.4 ± 1.0
B (mm)	50 min
C (mm)	13 ± 0.8
D (mm)	178 ± 2

Tearing off force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

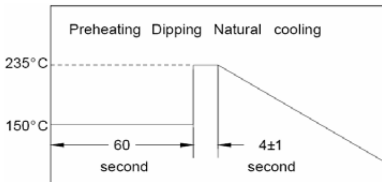
Packaging Quantity

Type	PCS / Reel
SCWL252010XXXXQ	2,000

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Reliability and Test Condition

Test Item	Performance	Test Method and Remarks			
Operating Temperature	-55 ~ +125°C (For products in unopened tape package, less than 40 °C)				
Electrical Performance Test					
Inductance L	Refer to standard electrical characteristic list	Agilent-4291, Agilent-4287			
Q		Agilent-4192, Agilent-4285			
SRF		Agilent-4192			
DC Resistance		Agilent-4338			
Rated Current	Base on temp. rise & $\Delta L/L0A \leq 30\%$	Saturation DC Current (Isat) will cause L0 to drop approximately $\Delta L(\%)$			
Mechanical Performance Test					
Solder Heat Resistance	Appearance: No damage Temperature Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate	Number of heat cycles
		260 ± 5 (Solder Temp)	10 ± 1	25mm/s ± 6 mm/s	1
		Depth: completely cover the termination			
Solderability Test	More than 95% of terminal electrode should be covered with solder	 After fluxing, component shall be dipped in a melted solder bath at 235$\pm 25^\circ$ C for 4± 1seconds			
Reliability Test					
Life Test	Appearance: No damage Inductance: within $\pm 10\%$ of initial value Q: shall not exceed the specification value. RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times. IPC/JEDEC J-STD-020D Classification Reflow Profiles Temperature: 125 $\pm 2^\circ$ C(Bead) Temperature: 85 $\pm 2^\circ$ C(Inductor) Applied current: rated current Duration: 1000 ± 12 hrs Measured at room temperature after placing for 24 ± 2 hrs			
Thermal shock		Preconditioning: Run through IR reflow for 2 times. IPC/JEDEC J-STD-020D Classification Reflow Profiles Step1: -40 $\pm 2^\circ$ C 30 ± 5 min Step2: 25 $\pm 2^\circ$ C ≤ 0.5 min Step3: 105 $\pm 2^\circ$ C 30 ± 5 min Number of cycles: 500 Measured at room temperature after placing for 24 ± 2 hrs			
Humidity Resistance Test		Preconditioning: Run through IR reflow for 2 times. IPC/JEDEC J-STD-020D Classification Reflow Profiles Humidity: 85 $\pm 2\%$ R.H, Temperature: 85 $^\circ$ C $\pm 2^\circ$ C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24 ± 2 hrs			
Vibration Test		Preconditioning: Run through IR reflow for 2 times. IPC/JEDEC J-STD-020D Classification Reflow Profiles Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude: 0.15mm $\pm 10\%$ Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations)			